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Has received an application for a patent for a new and useful invention. The title and description of the invention are enclosed. The requirements of law have been complied with, and it has been determined that a patent on the invention shall be granted under the law.

Therefore, this

United States Patent

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Michelle K. Lee

Director of the United States Patent and Trademark Office



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(54) **LAMP MODULE**

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See application file for complete search history.

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(57) **ABSTRACT**

A lamp module includes a cover structure, a circuit board structure and a multichip package structure, and the circuit board structure and the multichip package structure are sequentially assembled on the bottom side of the cover structure. The cover structure includes a cover body, a plurality of positioning elements disposed on the bottom side of the cover body, and a plurality of retaining elements disposed on the bottom side of the cover body. The cover body has a through opening and a surrounding light-reflecting surface formed on the inner surface of the through opening. The circuit board structure is disposed on the bottom side of the cover body and includes a plurality of conductive pins disposed on the bottom side of the circuit board structure. The multichip package structure is disposed on the bottom side of the cover body and electrically connected to the circuit board structure.

10 Claims, 7 Drawing Sheets

